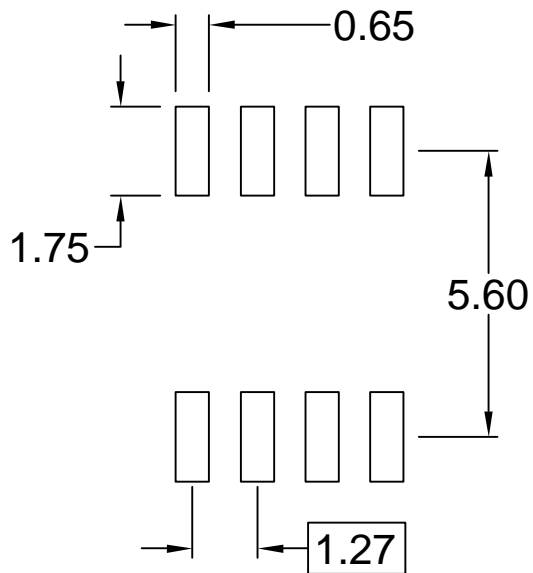
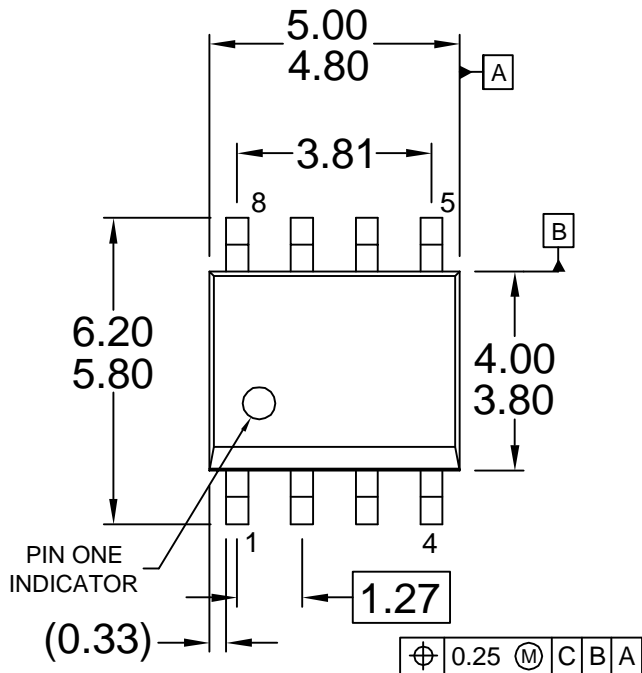
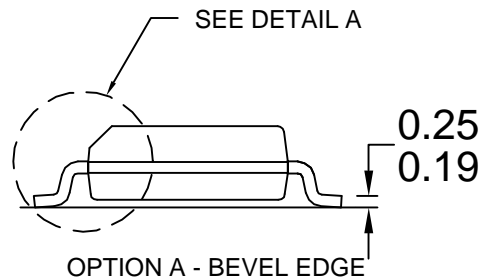
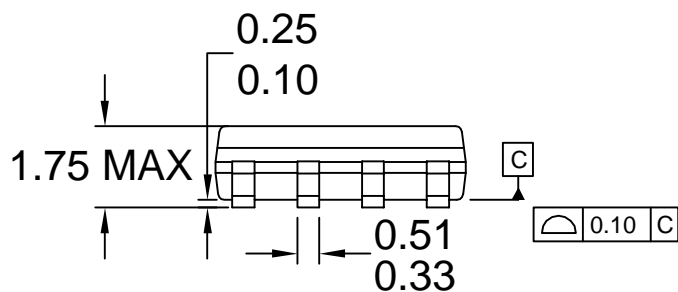


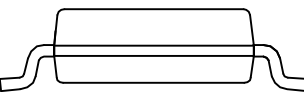
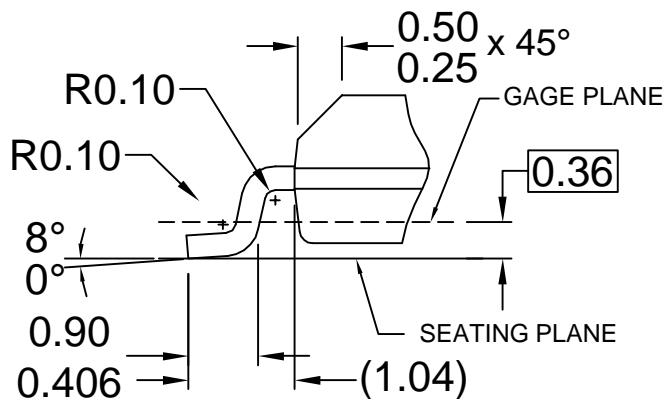
REVISIONS			
LTR	DESCRIPTION	DATE	BY/APP'D
12	CHANGED LEADSPREAD, TERMINAL WIDTH, AND FOOT LENGTH, REMOVED REFERENCE TO LEAD FINISH.	27 JULY 07	L.HUEBENER
13	ADDED OPTION "A" AND "B" VIEW	19 SEPT 07	H.ALLEN



LAND PATTERN RECOMMENDATION



OPTION A - BEVEL EDGE



OPTION B - NO BEVEL EDGE

DETAIL A  
SCALE: 2:1

NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE CONFORMS TO JEDEC MS-012, VARIATION AA, ISSUE C,
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
- D) LANDPATTERN STANDARD: SOIC127P600X175-8M.
- E) DRAWING FILENAME: M08AREV13

APPROVALS	DATE	FAIRCHILD SEMICONDUCTOR			
DRAWN: H.ALLEN	19 SEPT 07				
DFTG. CHK: SSI. CHOI	20 SEPT 07	8LD, SOIC, JEDEC MS-012, 0.150" NARROW BODY			
ENGR. CHK:					
PROJECTION		SCALE: N/A	SIZE: C	DRAWING NUMBER: MKT-M08A	REV: 13
DO NOT SCALE DRAWING		SHEET: 1 of 1			